ISC Audits & Reviews SC Summary (July 15th, 2025)

Doc.	**Title**	**Vote**
6601B;	New Standard: Guide for Meeting IRDS Yield Table Recommendations for High Purity Polymer Materials and Components Used in Ultrapure Water;	Passed
6938C;	New Standard: Guide for Equipment Edge Data Governance;	Passed
7169;	Revision of SEMI S10-0423E, Safety Guideline For Risk Assessment And Risk Evaluation Process With Change Of Title To: Safety Guideline For Risk Assessment And Risk Evaluation Processes	Passed
7234;	New Standard: Specification for Electronic Supply Chain Traceability Using Distributed Ledger Technology;	Passed
7270-LI1;	Changes to address references that are no longer valid or no longer needed;	Passed
7293;	New Auxiliary Document: Report on Closing Metrologies Gaps for Wafer Measurements at Different Stages of CMP Process ;	Passed
7311A-LI1;	Add additional requirements and clarifications to cybersecurity status information to be reported;	Passed
7311A-LI2;	Address issues raised by TF members;	Passed
7329-LI1;	Correction of inequality sign in Figure 2 and add the extended flange area to Figure 18	Passed
7337;	Reapproval of SEMI 3D9-0914 (Reapproved 0420), Guide for Describing Materials Properties for a 300 mm 3DS-IC Wafer Stack;	Passed
7338;	Reapproval of SEMI 3D10-0814 (Reapproved 0420), Guide to Describing Materials Properties for Intermediate Wafers for Use in a 300 mm 3DS-IC Wafer Stack ;	Passed
7339;	Reapproval of SEMI 3D11-1214 (Reapproved 0420), Terminology for Through Glass Via and Blind Via in Glass Geometrical Metrology ;	Passed
7340;	Reapproval of SEMI MS2-1113 (Reapproved 0819), Test Method for Step Height Measurements of Thin Films;	Passed
7341;	Reapproval of SEMI MS5-0813 (Reapproved 0819), Test Method for Wafer Bond Strength Measurements Using Micro-Chevron Test Structures;	Passed
7342;	Reapproval of SEMI MS12-0220, Specification for Silicon Substrates Used in Fabrication of MEMS Devices;	Passed
7343;	Reapproval of SEMI E177-0919E, Specification for Transmission Electron Microscope (TEM) Lamella Carriers Used in Electron Microscopy Workflows;	Passed
7347;	Reapproval of SEMI E54.18-0914 (Reapproved 0420) - Specification for Sensor/Actuator Network Specific Device Model for Vacuum Pump Device;	Passed
R7139;	Line Item Revisions to E40-0324, Specification For Processing Management and E40.1-1218 (Reapproved 0324), Specification For SECS-II Protocol For Processing Management; Line Item 1 - Changes to E40 and E40.1 as shown	Passed
R7140;	Line Item Revisions to E94-0324, Specification For Control Job Management and E94.1-0312 (Reapproved 0324), Specification For SECS-II Protocol For Control Job Management (CJM); Line Item 1 - Changes to E94 and E94.1 as shown	Passed
M52-0525	Guide for Specifying Scanning Surface Inspection Systems for Silicon Wafers for the 130 nm to 5 nm Technology Generations (Type 2 Editorial Changes)	Passed
S2-0724	Environmental, Health, and Safety Guideline for Semiconductor Manufacturing Equipment (Type 2 Editorial Changes)	Passed

For more information, please contact the SEMI Standards Engineer/Coordinator. (http://www.semi.org/standards/contacts) nearest you.

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